Tektronix

半导体材料与器件科学云讲堂

——超快脉冲在先进的NVM测试中的应用及神经元 网络测试前瞻

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Tektronix

Non-Volatile Memory Using Pulse Techniques & Synapsis networking Tester

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Non-Volatile Memory

- Used for storing data
 - Database servers
 - Personal computers
 - Smartphones and other devices
 - Automobiles
 - Home appliances
 - Industrial machines
- Traditional technologies
 - Hard Disk Drives (magnetic)
 - Magnetic tape and floppy drives (magnetic)
 - CD, DVD, BluRay, Laser Disk (Optical)



Non-Volatile Memory

TECHNOLOGIES

- NAND flash has ruled for years
 - Floating gate technology
 - Thumb drives, SSD, Smart phones, etc.
 - Majority of the market still
- Researchers are developing new memory technologies
 for better performance
 - Phase change memory (PRAM)
 - Resistive memory (ReRAM)
 - Magnetoresistive memory (MRAM)
 - And others!



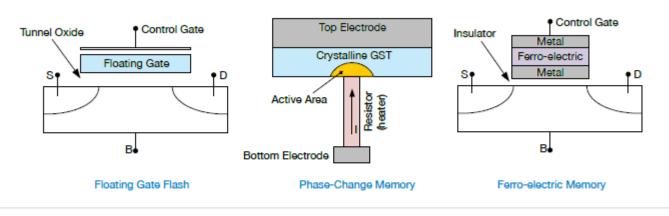


Figure 1. Various non-volatile memory devices.

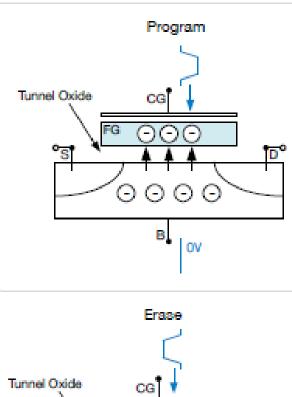
Non-Volatile Memory Emerging Technologies

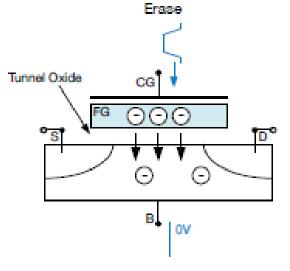
NVM Type	How it Works
Floating Gate Flash	Charges and discharges the floating gate to create the "1" and "0" logic
Phase Change (PRAM)	Cells are switched from an ordered crystalline phase to a disordered, amorphous phase.
Magnetoresistive (MRAM)	Polarity is changed in one of two ferromagnetic plates to provide memory storage.
Ferro-electric (FeRAM)	The memory mechanism is based on a polarization shift in ferroelectric materials.
Redox (ReRAM)	A filament is formed through a dielectric and can be reset or set by an applied voltage.
Conductive-bridging (CBRAM)	Memory storage is based on the physical re-location of ions within a solid electrolyte.
NanoRAM (NRAM)	Uses Carbon Nanotube Transistors (CNT) which are placed in two or more resistive modes.
SONOS	"Silicon-Oxide-Nitride-Oxide-Silicon". Closely related to Flash NVM but uses silicon nitride.

Floating Gate Technology

FG NVM

- Similar to a Silicon-Based FET
 - Gate, Drain, Source, Bulk
- Contains a second, floating gate
 - Tunneling or Hot Carrier Injection trap a charge
 - Allows the FET to "remember"
- Can be produced with familiar technology
 - We are very good at creating silicon devices
- Does have some downsides
 - Can be slow
 - Degrades
 - Scalability (Floating gate can only be so small)





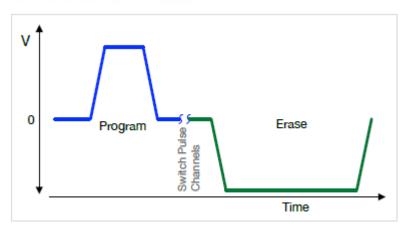
Testing FG NVM with Pulsing

PULSE MEASURE UNIT (PMU) WITH 4200A

- Pulses to perform functions
 - Program, Erase, and Read functions
- PMU allows testing at close to real-world conditions
- Endurance testing
 - Increase number of program/erase cycles logarithmically until memory cell fails
 - PMU can read/write millions of cycles



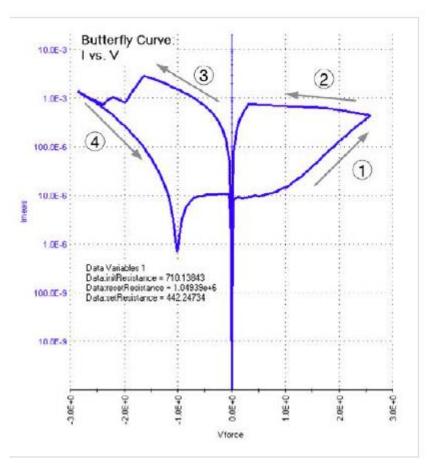
Figure 2. 4225-PMU Ultra-Fast I-V Module and two 4225-RPM Remote Amplifier/Switch Modules.



Testing New Memory Material

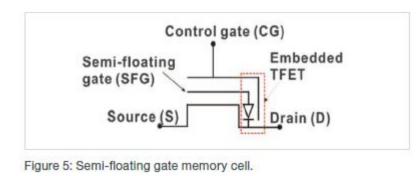
RESISTIVE MEMORY (RERAM)

- Similar to testing FG NVM
- Requires different values and timings
- Reliability/Endurance testing is very important
 - These are untested technologies



What if I Need to Go Faster?

- Even the PMU has limitations
 - $\circ~$ 70ns pulses at 10V and 200mA
 - 20ns absolute minimum pulse
- Newer FG NVM can go fast
 - $\,\circ\,$ Below device can be read in ~1ns



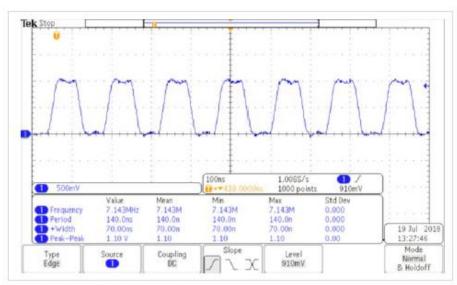


Figure 2: Recommended minimum pulse width using the 4225-PMU.

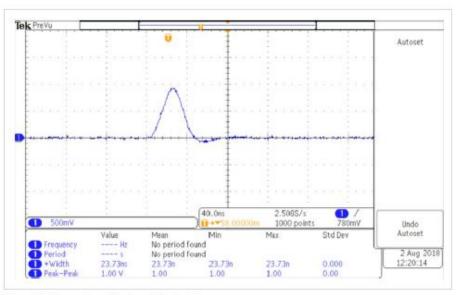
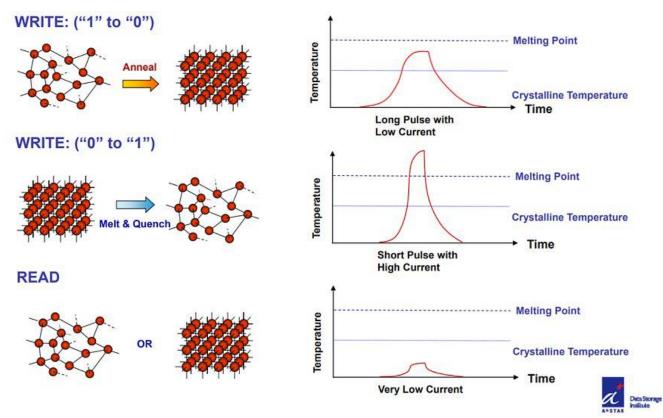


Figure 3: Minimum pulse width allowed by the software.

Phase Change Memory (PCRAM)

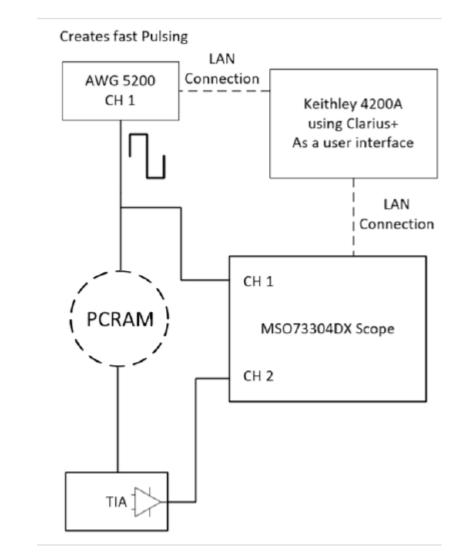
- Different functions require different pulses.
- Need to control many factors
 - Pulse duration
 - Off time
 - Pulse voltage
 - Pulse current



Nanosecond Pulse Setup

2 TERMINAL SETUP

- Good for 2 terminal memory cells like PCRAM, ReRAM, and MRAM.
- This setup is a bit more complicated than the previous with just the PMU
 - 4200A for control and data gathering
 - AWG for pulsing
 - Oscilloscope for measuring response
 - TIA for converting current to voltage





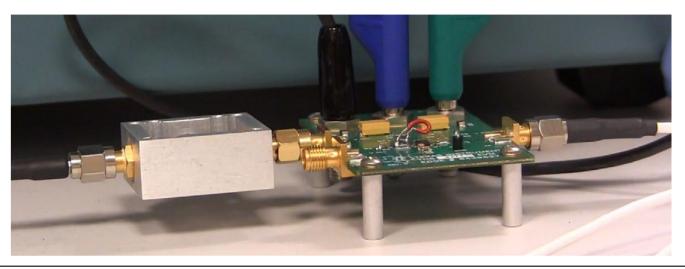
Fast and Low Current

- Very tricky measurements
- Low current measurements are very prone to noise
 - Thermal noise
 - EMI noise
 - Photoelectric effects
- Low current measurements typically require a long integration time



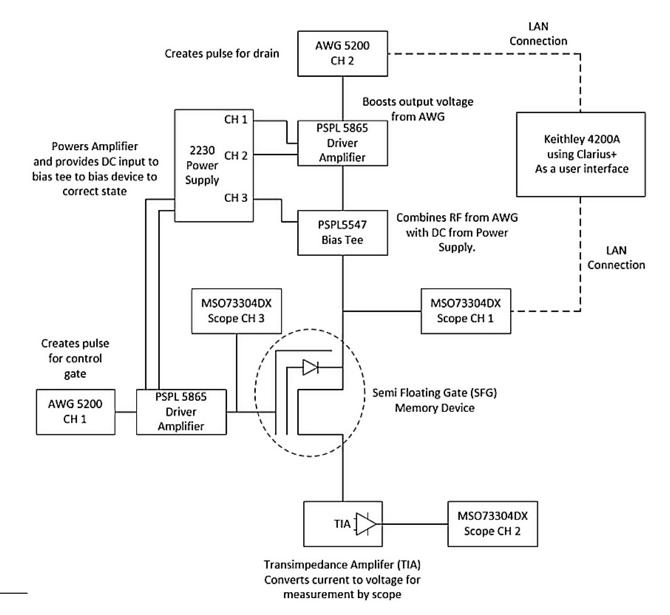
Transimpedance Amplifier

- Current-to-voltage converter
- Typically used in sensor applications to amplify current output
- Need to pick carefully
 - Some are very noisy or have very large offsets
 - Different applications can tolerate different amounts of error



Three Terminal Setup

- This device required three terminals, higher power, and DC biasing
- Required some tweaks
 - Addition of amplifiers
 - Addition of bias tees
 - Upgrade to a 4-channel scope
 - Addition of a 3-channel power supply
- Still used AWG, TIA, and 4200A





Physical test setup

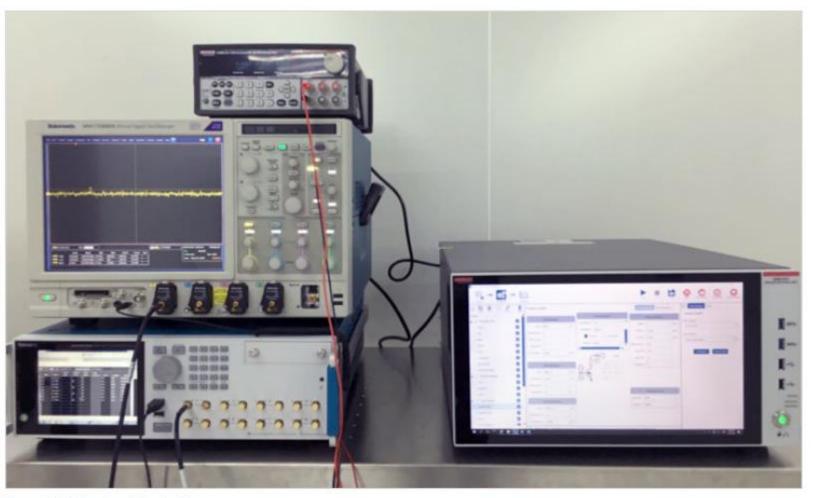


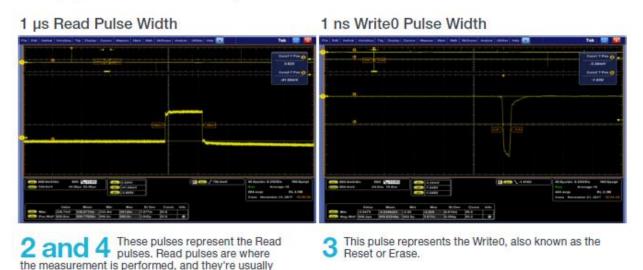
Figure 11: Tektronix solution testing.



- Ultra-fast pulsing is required for the development of new NVM devices
- Keithley 4225-PMU is excellent at this type of testing
- When higher speeds are needed, we need to get creative
- Tektronix's solution allows memory pulse testing down to <1ns

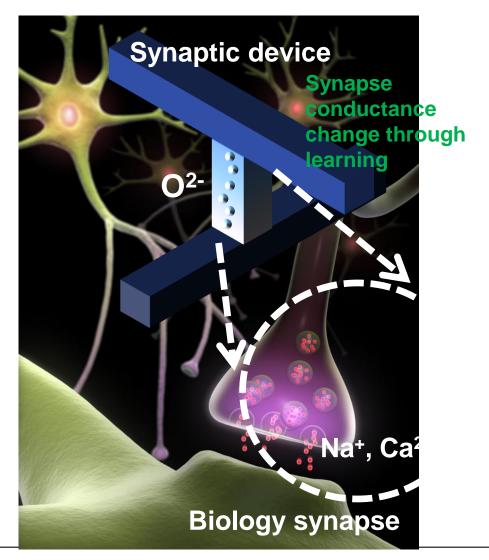


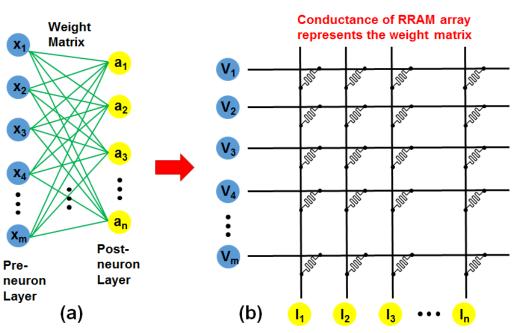
These pulses represent the Write1 pulse, also known as the Set Pulse. 1 ns pulse width is shown here, as well as a 200 ps pulse width to show the AWG capabilities.



long pulses.

RRAM Properties is similar to SynapseFrom Tinghua University Prof. GaoBin





- ➢ RRAM properties is similar to synapse → electronic synapse
- RRAM can realize in-memory computing, solving von Neumann bottleneck
- Crossbar or 3D architecture could support large RRAM in parallel

Device Cell characterization Steps



Forming

Verify the resistor before and after forming, higher voltage than Vset, typical no specified testing step and being combined with Cell IV Characterization



High speed pulse testing

Device cell set/reset testing, opt. with verification steps



Cell I-V-t characterization

Testing the set/reset HRS/LRS I-V character, with slow t for basis memristor testing.



Data Retention

After write the cell, keep reading with time/temperature conditions



Cell Endurance

High frequency write (set/reset) and keep reading for cell performance variation checking

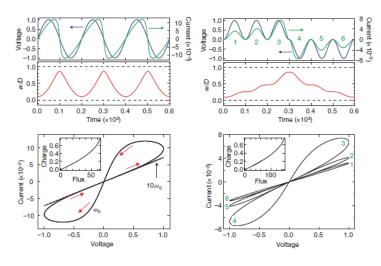
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Device Cell I-V-t Characterization

- I-V-t Test Condition
 - 1x SMU, Opt. 1x PMU
 - V_{Set/Reset} @<10V, I @>nA range, t
 @>50ns interval
 - I-V Sweep, Opt. Pulsed I-V
- Solution
 - HW: Parameter Analyzer
 - 4200A-SCA
 - 4200-SMU
 - 4225-PMU
 - Manual Probe Station
 - SW: Clarius

Type of analog RRAM	Ag:a-Si [2]	TaO _x /TiO ₂ [3]	РСМО [4]	AlOx/HfO ₂ [5]	ETML/HfO _x (0.8mΩ·cm)	ETML/HfO _x (4.4mΩ·cm)	$\begin{array}{c} \text{ETML/HfO}_{x}\\ (30.4\text{m}\Omega\cdot\text{cm}) \end{array}$	ETML/HfO _x (2 parallel)	Ideal analog RRAM
Nonlinearity (SET)	2.40	0.66	3.68	1.94	0.96	0.93	0.04	0.08	0
Nonlinearity (RESET)	-4.88	-0.69	-6.76	-0.61	-3.26	-2.63	-0.63	-0.63	0
On-state resistance	26 MΩ	5 MΩ	23 MΩ	17 KΩ	10KΩ	30kΩ	100kΩ	50kΩ	High
ON/OFF ratio (analog region)	12.5	2	6.8	4.4	10	10	10	10	Large
SET pulse	3.2V/300µs	3V/40ms	2V/1ms	0.9V/100µs	1.7/50ns	1.5V/50ns	1.6V/50ns	1.6V/50ns	Low voltage Fast speed
RESET pulse	2.8V/300µs	3V/10ms	2V/1ms	1V/100μs	1.5V/50ns	1.5V/50ns	1.5V/50ns	1.5V/50ns	Low voltage Fast speed
Variation	3.5%	<1%	<1%	5%	3%	3.35%	3.7%	1.5%	0%

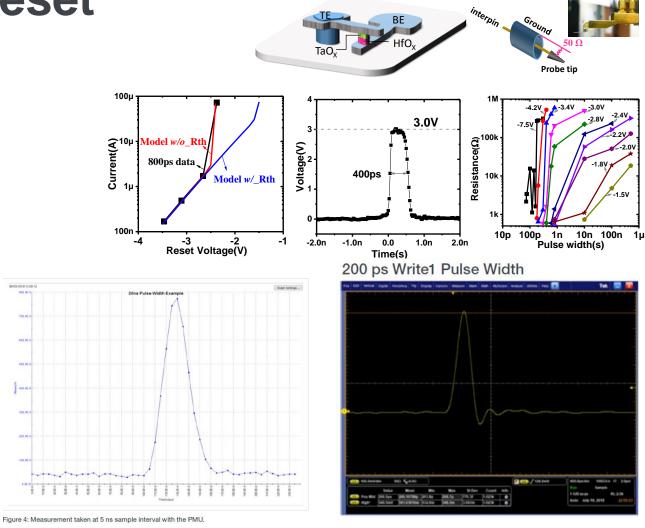




Device Fast Pulse Set/Reset

- Fast Pulse Set/Reset
 - Device speed performance
 - Removing the self-heating effect by longer set/reset time
- Solution:

Solution	~50ns Pulse	<1ns Pulse	
HW	4200A-SCS, 4200-SMU, 4225-PMU	AWG5200, MSO/DPO70000	
SW	Clarius	Customized SW	
Pulse Width Typ.	70ns @ 10V, 200mA range	<1ns	
Pulse Width Min.	20ns	200ps	
Reading Speed	200MSa/s	100GSa/s	
TIA	N/A	Opt. from FEMTO	



KEI 4225-PMU

Min 20ns pulse generating

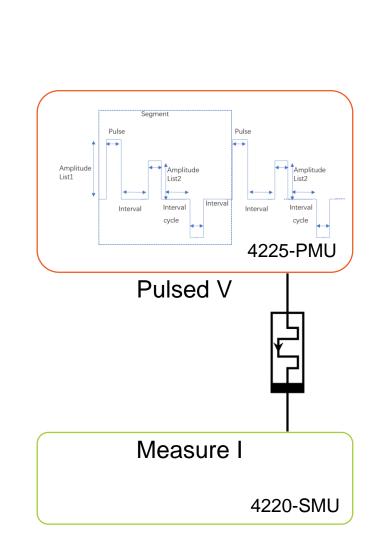
· Fast 200MSa/s (5ns interval) Reading

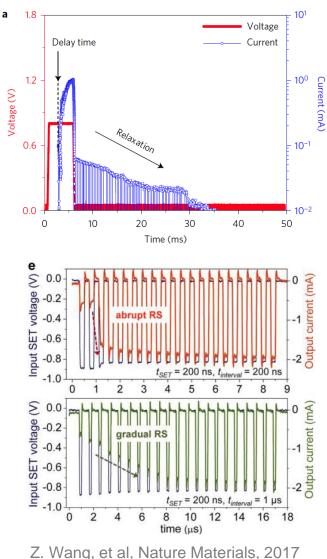
TEK AWG5200, MSO/DPO70000

- Min 200ps pulse generating
- Fast 100GSa/s (10ps interval) Reading

Device Resistance Dynamics Test

- Synapsis Cell Charaterization
- Pulsed I-V-t, lower self-heat
- Solution
 - HW: Parameter Analyzer
 - 4200A-SCA
 - 4200-SMU
 - 4225-PMU
 - Manual Probe Station
 - SW: Clarius w/ customized project

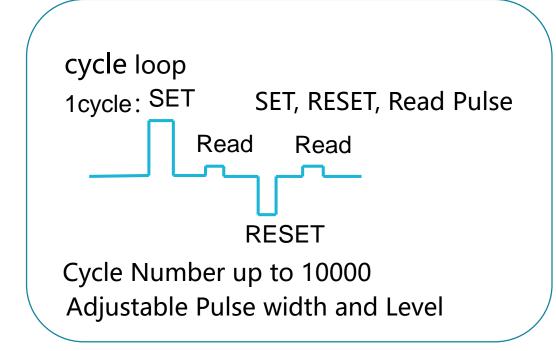




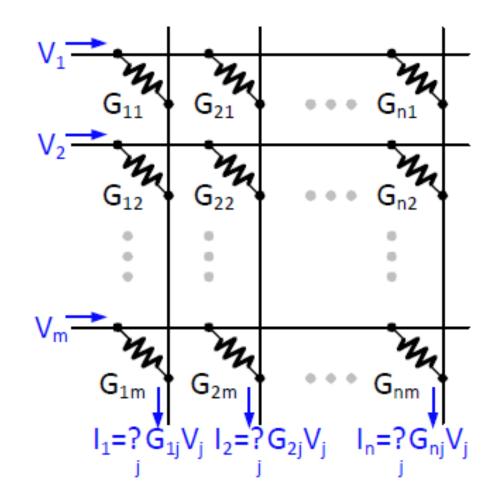
C. Du et al, Nano Letters, 2015, 15, 2203

Device Endurance Test

- RRAM Cycling R/W
 - Set/Reset
 - Pulse Set/Reset
 - Memory Retention, long time pulse
- Solution:
 - HW: Parameter Analyzer
 - 4200A-SCA
 - 4200-SMU
 - 4225-PMU
 - Manual Probe Station
 - SW: Clarius w/ customized project



Array Testing & Synapsis networking

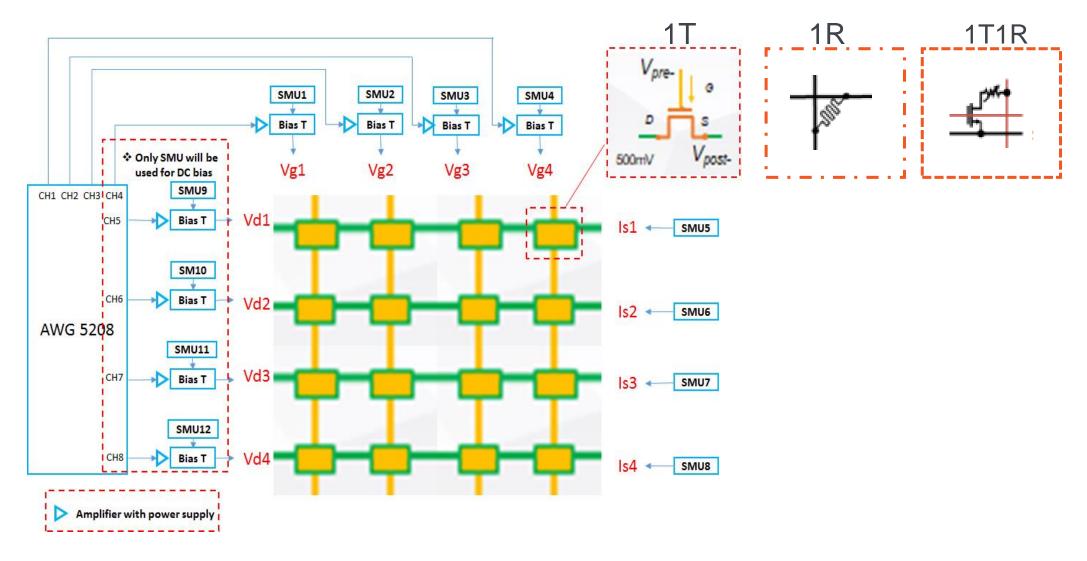


Array and Synapsis networking testing is challenge and hot application in near future.

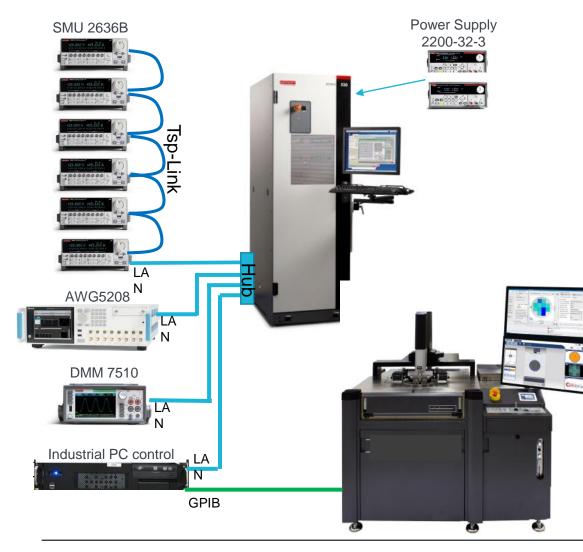
The basic concept of Synapsis networking testing is to apply different pattern on WL simultaneously, and read back current on BL at same time. The tester need pure parallel testing capability with high synchronism, high quality pulse waveform from nS - mS and low level measurements capability.

To achieve in-lab device characterization testing, We try to set up "Per-Pin" structure and integrate instruments to meet all challenges.

Array Tester Concept



Array Tester Concept



- Wafer level semiauto leading research Synapses networking – Array Testing
- SMU Per-Pin test structure
- From <1nS to mS customized pulse Train
- Outstanding integration capability include prober driver, test sequence control, complex instruments integration and Expertise to handle Low Level to RF testing

Additional Material and Documentation

- 1 ns Pulsing Solutions for non-Volatile Memory Testing
- Pulse I-V Characterization of Non-Volatile Memory Technologies
- <u>4200A Datasheet</u>
- Documentation in Clarius⁺ software

Datasheet					
PMU Pulse Timing					
	10 V Range Source Only	10 V Range with Measure	40 V Range Source Only	40 V Range with Measure	
Frequency range	1 Hz to 50 MHz	1 Hz to 8.3 MHz	1 Hz to 10 MHz	1 Hz to 3.5 MHz	
Timing resolution	10 ns	10 ns	10 ns	10 ns	
RMS Jitter (period, width), typical	0.01% + 200 ps	0.01% + 200 ps	0.01% + 200 ps	0.01% + 200 ps	
Period range	20 ns to 1 s	120 ns to 1 s	100 ns to 1s	280 ns to 1s	
Accuracy	±1%	±1%	±1%	±1%	
Pulse width range	10 ns to (Period–10 ns)	60 ns to (Period-10 ns)	50 ns to (Period-10 ns)	140 ns to (Period-10 ns)	
Accuracy	±(1% + 200 ps)	±(1% + 200 ps)	±(1% + 5 ns)	±(1% + 5 ns)	
Programmable transition time (0%-100%)	10 ns to 33 ms	20 ns to 33 ms	30 ns to 33 ms 1	100 ns to 33 ms	
Transition slew rate accuracy	±1% (transitions > 100 ns)	±1% (transitions > 100 ns)	±1% (transitions > 1 µs)	±1% (transitions > 100 ns)	
Solid state relay open/close time	25 µs	25 µs	25 µs	25 µs	
Notes 1.40V range minimum programmable transition Voltage Source, Best Per When the 4225-PMU is used as a volt s provided to offer a clearer idea of be interpreted as a quarantee.	formance age source only (no measurem	nents of voltage or current),			
		10V Ran	De	40V Range	
	Rise time	<10 ns		50 ns to 10 V, 100 ns to 40 V 50 ns (FWHM)	
			140		
	Pulse width	10 ns (FW	HM)	50 ns (FWHM)	
	Pulse width Period	10 ns (FW 20 ns	нм)	50 ns (FWHM) 100 ns	

